



## SSC8031GQ4

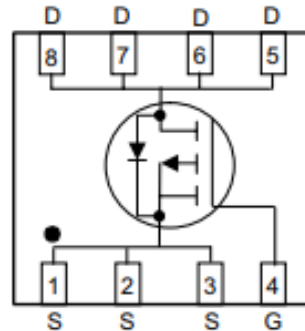
### P-Channel Enhancement Mode MOSFET

#### ➤ Features

VDS	VGS	RDSON Typ.	ID
-30V	±20V	10mR@-10V	-29A
		14mR@-4V5	

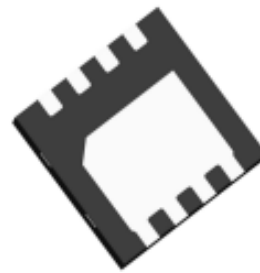
#### ➤ Pin configuration

Top view



#### ➤ Description

This device is produced with high cell density DMOS trench technology, which is especially used to minimize on-state resistance. This device is particularly suited for low voltage power management requiring a wide range of given voltage ratings(4.5V~25V) such as load switch and battery protection.



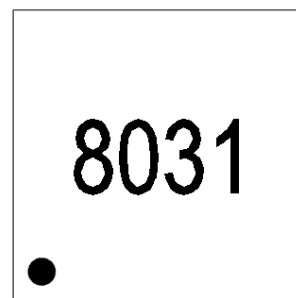
Bottom View

#### ➤ Applications

- Load Switch
- NB battery
- DCDC conversion

#### ➤ Ordering Information

Device	Package	Shipping
SSC8031GQ4	DFN3x3	5000/Reel



Marking



➤ **Absolute Maximum Ratings**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain-to-Source Voltage	-30	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current <sup>a</sup>	-29	A
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	-85	A
$P_D$	Power Dissipation <sup>c</sup>	27	W
$P_{DSM}$	Power Dissipation <sup>a</sup>	3.5	W
$T_J$	Operation junction temperature	-55 to 150	$^{\circ}\text{C}$
$T_{STG}$	Storage temperature range	-55 to 150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter	Typical	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>		39	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance		4.8	

Note:

- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user is specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

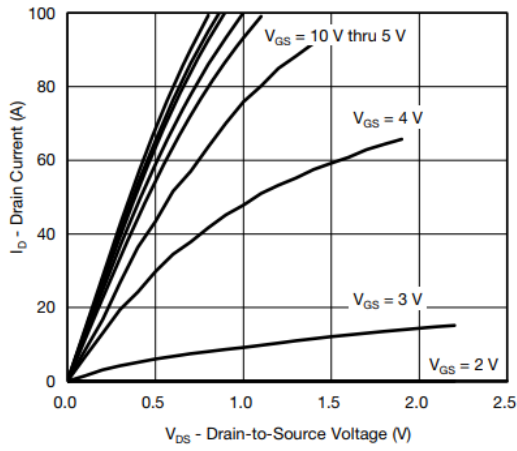


➤ **Electronics Characteristics**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

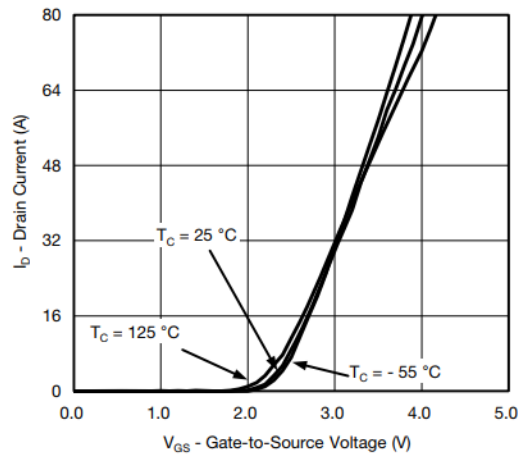
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-1.6	-3	V
$R_{DS(on)}$	Drain-Source On- Resistance	$V_{GS}=-10V, I_D=-10A$		10	12	mR
		$V_{GS}=-4.5V, I_D=-7A$		14	16	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-30V, V_{GS}=0V$			-1	$\mu A$
$I_{GSS}$	Gate-Source leak current	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
$G_{FS}$	Transconductance	$V_{DS}=-5V, I_D=-10A$		18		S
$V_{SD}$	Forward Voltage	$V_{GS}=0V, I_S=-1A$		-0.75	-1.6	V
$C_{iss}$	Input Capacitance	$V_{DS}=-20V, V_{GS}=0V, f=1MHz$		2000		pF
$C_{oss}$	Output Capacitance			550		
$C_{rss}$	Reverse Transfer Capacitance			800		
$Q_g$	Total Gate charge	$V_{GS}=-4.5V, V_{DS}=-15V, I_D=-7A$		24		nC
$Q_{gs}$	Gate to Source charge			8		
$Q_{gd}$	Gate to Drain charge			12		
$T_{D(ON)}$	Turn-on delay time	$V_{GS}=-10V,$ $V_{DS}=-15V, R_L=1.5R, R_G=3R$		8.6		ns
$T_r$	Rise time			7		
$T_{D(OFF)}$	Turn-off delay time			39		
$T_f$	Fall time			10		



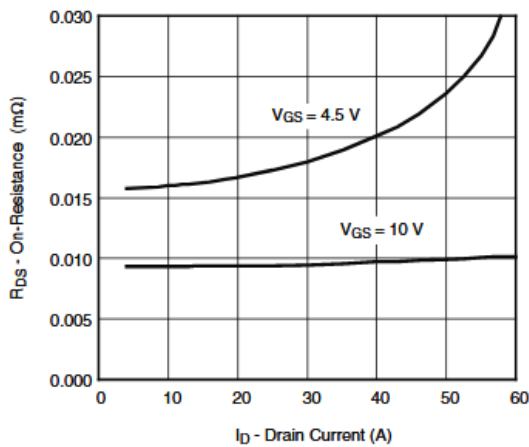
➤ **Typical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise noted)



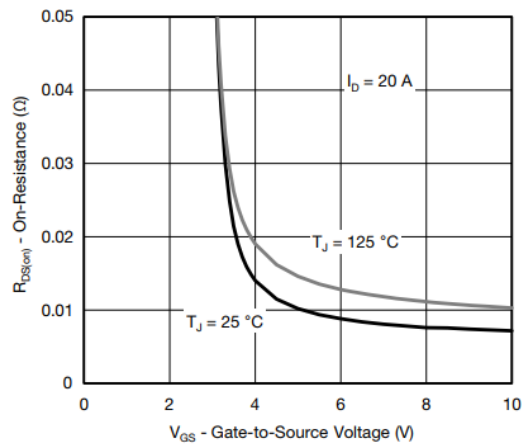
**Output Characteristics**



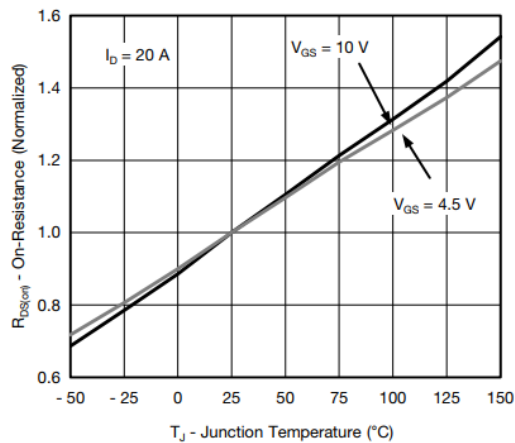
**Transfer Characteristics**



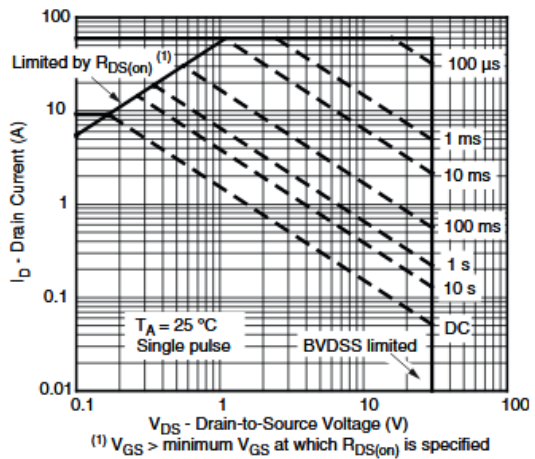
**On-Resistance vs. Drain Current and Gate Voltage**



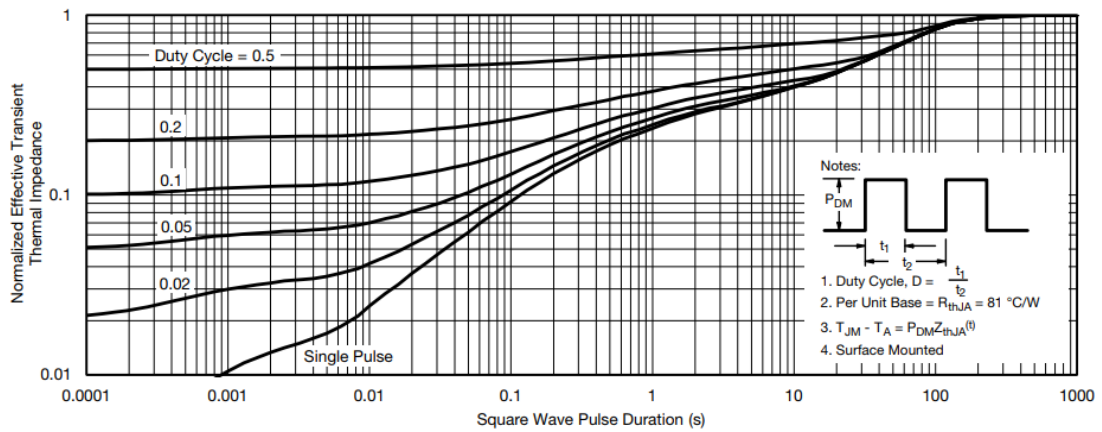
**On-Resistance vs. Gate-to-Source Voltage**



**On-Resistance vs. Junction Temperature**



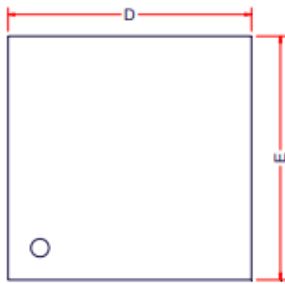
**Safe Operating Area, Junction-to-Ambient**



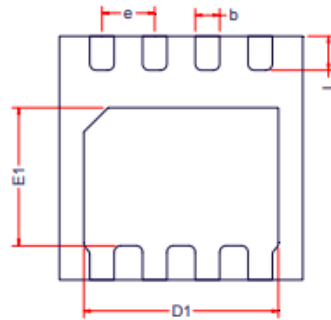
Normalized Thermal Transient Impedance, Junction-to-Ambient



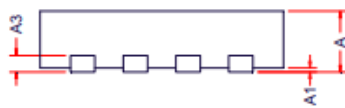
➤ Package Information



TOP VIEW



BOTTOM VIEW



SIDE VIEW

DFN3x3-8L

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2	0.20Ref		
D	2.90	3.00	3.10
E	2.90	3.00	3.10
D1	2.35	2.40	2.45
E1	1.65	1.70	1.75
b	0.25	0.30	0.35
e	0.65BSC		
L	0.37	0.42	0.47



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